

LUMIS



•HIGH-POWER CERAMIC PACKAGING LED –3535 RGB SERIES L35C-RGB13C1F-LSLV

















Product Brief(产品简介)

Description (描述)

- . This surface-mount LED size is standard package: 3.5x3.5x1.1mm
 . The L35C series is designed for high
- . The L35C series is designed for high flux output applications with high current operation capability.

Features And Benefits (特性优点)

- . Designed for high current operation
- . Low thermal resistance
- . Pb-free reflow soldering application

Key Applications (应用)

- Indoor lighting
- Outdoor lighting
- Architectural lighting
- Industrial lighting
- Plant Factory
- •Flower Production
- •Tissue Culture
- Refreshment

Table 1. Product Selection Table (产品目录)

_	Peak Wavelength			
Parameter	Color	Min.	Max.	
L35C-RGB13C1F-LSLV	Red	620	625	
	Green	520	525	
	Blue	455	460	



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Performance

Table 2. Electro Optical Characteristics (光电特性), Ta = 25℃, RH60%

Color	Luminous Flux (350mA)		
	Min.	Max.	
Red	50	55	
Green	100	110	
Blue	20	22	

Color	Wavelength Bin (nm)		
	Min.	Max.	
Red	620	625	
Green	520	525	
Blue	455	460	

- •Wavelength measurement tolerance is ± 2 nm.
- Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram.
- The luminous intensity Iv was measured at the peak of the spatial pattern which may not be aligned with the mechanical axis of the LED package.

• The lumen table is only for reference.



Performance

Table 3. Electro Optical Characteristics (光电特性), IF = 350mA , Ta = 25℃, RH60%

Item	Symbol	Color		Value		Unit	Test Condition
	<i>-</i> 3,20.	66.6.	Min.	Тур.	Max	Min.	
		Red	2.2	-	2.4		
Forward Voltage	VF	Green	3.0	-	3.2	V	IF=350mA
		Blue	3.0	-	3.2		
Reverse Current	IR	RGB	-	-	10	μΑ	VR=5V
Electrostatic Discharge	ESD	RGB	2000	-	-	V	НВМ
Thermal Resistance	sistance (Rth j-sp)	Red	-	18	-		
		Green	-	20	-	°C/W	IF=350mA
		Blue	-	18	-		

Table 4. Absolute Maximum Ratings (最大额定参数), Ta = 25℃, RH60%

Item	Symbol	Absolute Maximum Ratings	Unit
Forward Current	IF	400	mA
Power Dissipation	PD	R: 850; G/B: 1200	mW
Reverse Voltage	VR	5	V
Operating Temperature	Topr	-40∼+105	°C
Storage Temperature	Tstg	-40∼+105	°C
Junction Temperature	Tj	125	$^{\circ}$
Electrostatic Discharge	Tsld	230°C or 260°C for 10sec	-

- Tolerance of measurement of Luminous Flux or Radiometric Power: $\pm 10\%$
- Tolerance of measurement of wavelength: ± 2 nm
- Tolerance of measurement of Forward Voltage: \pm 0.05V
- All the data are just for reference, specific parameters refer to the label



Relative Spectral Distribution

Fig 1. Color Spectrum (光谱图), Ta = 25°C, RH60%

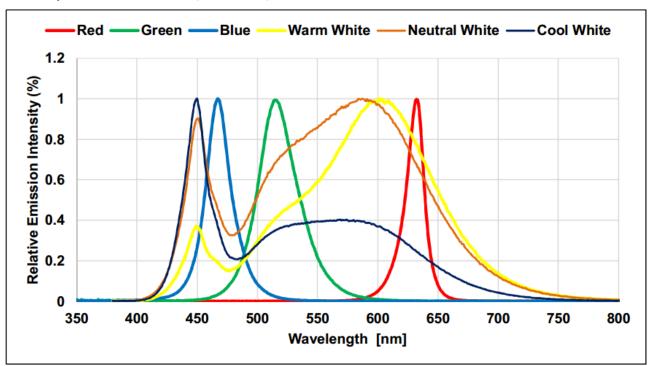
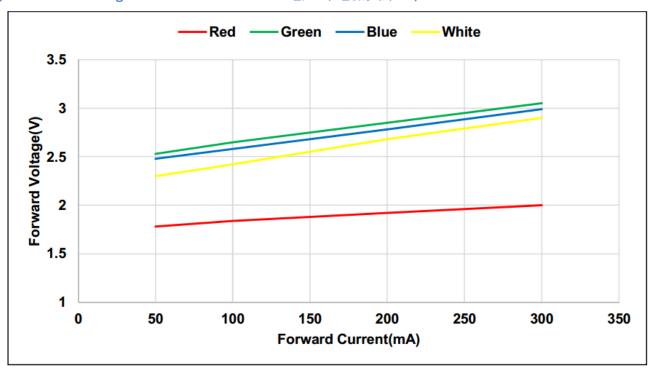


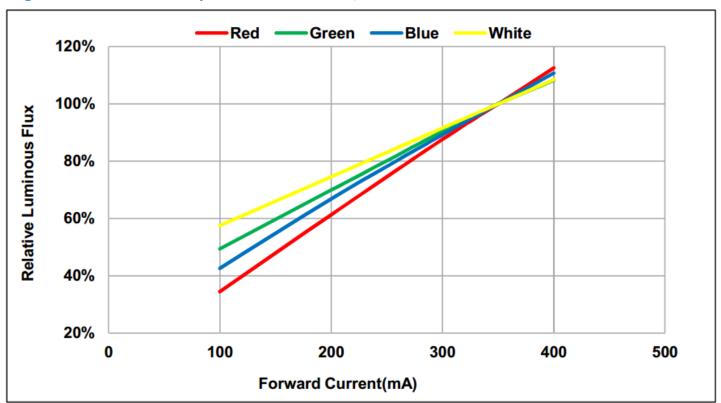
Fig 2. Forward Voltage vs. Forward Current (电压与电流关系), Ta = 25℃





Relative Spectral Distribution

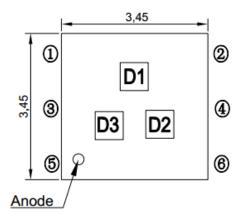
Fig 3. IF Vs. Relative Intensity (亮度与电流关系), Ta = 25℃

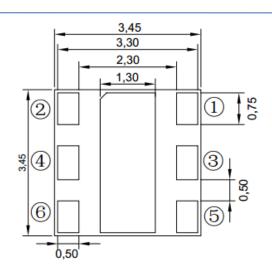




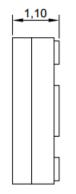
Outline Vs. Recommended Solder Pad

Fig 4. Mechanical Dimensions (产品尺寸)





- All dimensions are in millimeters.
- Scale: none
- Undefined tolerance: ±0.05mm.



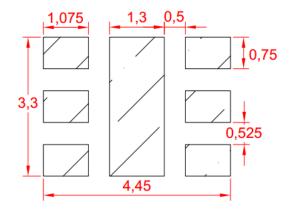
Color D1: Red D2: Green

D3: Blue

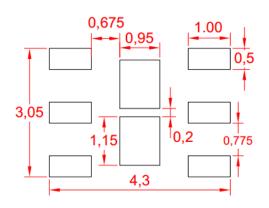




Fig 5. Recommended Solder Pad



Recommended PCB Solder Pad

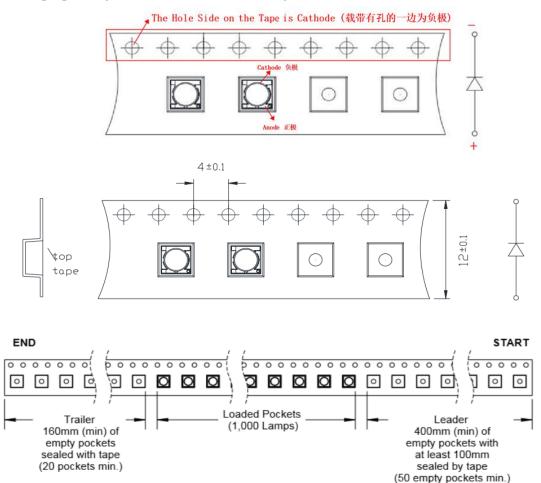


Stencil: 0.12mm
Recommended Stencil Pattern

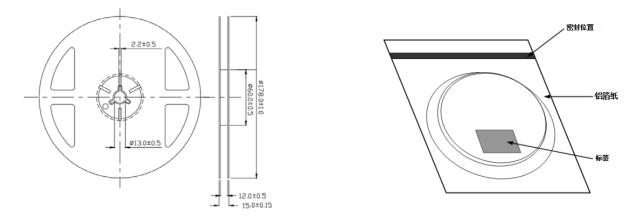


Packaging Information

Fig 6. Reel Packaging 1000pcs/Reel (卷带包装, 1000pcs/卷)



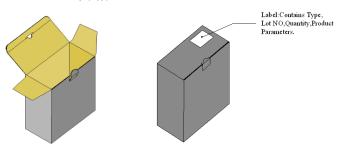
- Quantity: Max 1000pcs/Reel
- Cumulative Tolerance : Cumulative Tolerance/10 pitches to be \pm 0.25mm
- Adhesion Strength of Cover Tape Adhesion strength to be 0.1-0.7N when the cover tape is turned off from the carrier tape at the angle of 10° to the carrier tape.
- Package: P/N, Manufacturing data Code No. and Quantity to be indicated on a damp proof Package.





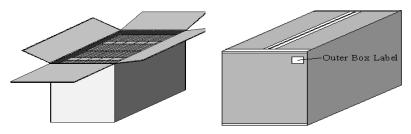
Packaging Information

Inner Box(内箱)



* Capacity 5 or 10 reels per box (内箱容量: 5或10卷)

Outer Box (外箱)



* Capacity 30 or 60 reels per box(外箱容量: 30或60卷)

Label (标签)





光通量中: 22 0 [lm] 色区 Color Bin: 电压 Vf: [V] 电流 IF: mA 数量 QTY: 5000PCS





Lot ID:

Country of Origin:CN Seal Date:2017

X1 X2 X3 X4 X5 X6 X7 X8

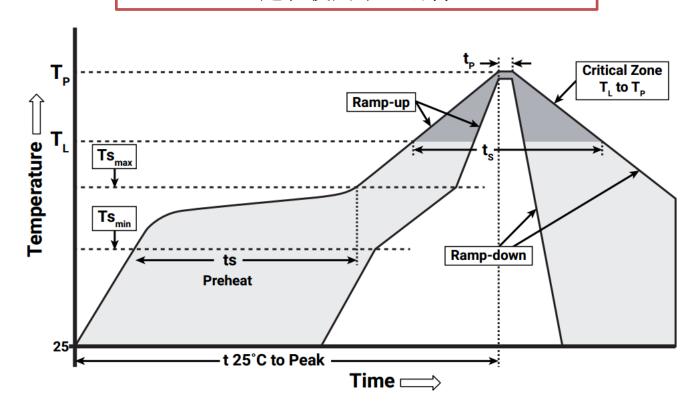
L 35 C - RGB 1 3 C1 F - LSLV

Item Number Code	Description	Item Number
X1	LED Type Code 产品代码	60: 6060; 30: 3030; 35: 3535;
X2	Light Color 发光颜色	W: White Color; C: Colored; I: IR; U: UV
Х3	Wavelength 波长	280: 280nm; 365: 365-370nm; 390: 395-400nm
X4	No. of Serial Chip 晶片串联数量	1-Z.
X5	No. of Parallel Chip 晶片并联数量	1-Z.
Х6	Lead Frame Code 支架代码	E1: EMC; E2: SMC; C1: Al₂O₃ Ceramic; C2: AlN Ceramic
X7	Viewing Angle 发光角度	A: 120 Deg. ; B: 30 Deg. ; C: 60 Deg. ; F: Flat
X8	Material Code 物料代码	LumiS Material Code



Reflow Soldering

Recommended Mid-Temperature Solder Paste 建议使用中温锡膏



Profile Feature	Lead-Free Solder
Average Ramp-Up Rate (Ts _{max} to Tp)	1.2 °C/second
Preheat: Temperature Min (Ts _{min})	120 °C
Preheat: Temperature Max (Ts _{max})	170 °C
Preheat: Time (ts _{min} to ts _{max})	65-150 seconds
Time Maintained Above: Temperature (T _L)	217 °C
Time Maintained Above: Time (t _L)	45-90 seconds
Peak/Classification Temperature (Tp)	235 - 245 °C
Time Within 5 °C of Actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	1 - 6 °C/second
Time 25 °C to Peak Temperature	4 minutes max.



Pre-caution

Caution

- 1. Reflow soldering is recommended not to be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.
- 2. Repairs should not be done after the LEDs have been soldered. When repair is unavoidable, suitable tools must be used.
- 3. Die slug is to be soldered.
- 4. When soldering, do not put stress on the LEDs during heating.
- 5. After soldering, do not warp the circuit board.

Notes on LumiS EMC Series soldering:

- 1. Recommend to use reflow machine.
- 2. Recommend to use heating plate soldering.
- 3. Manual soldering is not recommended.

Notes on reflow process:

- 1. To confirm whether the actual temperature curve in the reflow soldering conditions comply with recommended conditions. LEDs are guaranteed for one time reflow.
- 2. During reflow process do not apply force on LED active area.
- 3. After reflow process, PCB board should be cooled down before packing or storage.



Published by

Published By:

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Company Information

LumiS Technology Co., Ltd is located in Shen Zhen, China, which is a professional manufacturer of LED products that integrates research, production and sales. LumiS is a team focusing on LEDs, LED Modules and LED luminaries. To serve client better, we also provide other led lamp's accessories. Our experienced R&D team and sales team are young but professional. All of us have been serving customers over 4 years. We are aiming to provide full service on led luminaries solution from LEDs, driver to final production. Our engineers can offer the best solution when you design luminaries from the beginning. To be specific, when you design one luminary, LumiS can provide the LEDs with high quality and best price based on our professional knowledge. "Save Your Time, Improve Your Products".

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